# EVALUATION OF INNOVATIVE COOLING CONCEPTS WITH HIGH PERFORMANCE CARBON MATERIAL FOR VERTEX DETECTORS OPERATED IN VACUUM

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# OUTLINE

- I. Motivation
- 2. Thermal Pyrolithic Graphite (TPG)
- 3. Experimental Setup
- 4. Thermal Performance Measurements
- 5. Comparison to Simulation
- 6. Summary

# MOTIVATION



In-situ cooling is necessary because there are no cooling effects by convection.

#### Solution:

Materials with a high heat conductivity are a good option to transport the heat of the sensors to the cooling system.

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# THERMAL PYROLITHIC GRAPHITE

#### **TPG (Thermal Pyrolithic Graphite)**



Requirements to the carrier material	Features of TPG
Excellent heat conductivity (total heat input in a range of 200-500 $\frac{mW}{cm^2}$ )	in-plane heat conductivity (1600 W/mK ) heat conductivity in z-direction (20 W/mK)
Low material budget to avoid multiple scattering (0.3-0.5% <i>X</i> <sub>0</sub> )	Thickness chosen: 500 µm and 254 µm
Stability	Young's Modulus: 1050 Gpa Stiffness due to layered structure

# TPG STRUCTURE



The excellent thermal conductivity comes from a highly oriented crystal structure, which stacks in bulks.

# HEAT CONDUCTIVITIES IN COMPARISON



thermal conductivity [W/mK]

# EXPERIMENTAL SETUP



Kapton Heater by OMEGA LUX (heat load 790 mW/cm2)

TPG (Thermal Pyrolithic Graphite)

by Momentive (Thickness: 254 μm and 500 μm)

Liquid cooled Al- heat sink Huber CC-405 (0.7 kW)

backside

# **IR THERMOGRAPHY**

# Setup



#### IR Image (vacuum test stand)



VARIOCAM hr head by InfraTec

### THERMAL PERFORMANCE MEASUREMENTS



The thermal performance was characterized by analyzing heat-up curves of TPG with different thicknesses ( $254\mu m$  and  $500\mu m$ )

# THERMAL PERFORMANCE MEASUREMENTS: FAST RISE FIT



Fitting the heat- up curves during the first 15 seconds with

$$1 - \exp\left(-\frac{time}{\tau}\right)$$

$$\tau_{fast,TPG \ 254um} = 4.7s$$
  
$$\tau_{fast,TPG \ 500um} = 3.8s$$

$$\tau = \frac{l^2 \rho c}{\lambda}$$

The short relaxation times describe the excellent thermal performance of TPG (heat conductivity  $\lambda = 1600$  W/mK)

### THERMAL PERFORMANCE MEASUREMENTS: FAST RISE FIT



### THERMAL PERFORMANCE MEASUREMENTS: FAST RISE FIT



# MODELLING OF SIMULATION



# SIMULATION



#### **Goal** Finding a function which fits perfectly to our measurements

#### **Boundary condition**

- Fixed temperatures at two edges (0°C)
- Heater (4.5 x 4.5 mm<sup>2</sup>) in right corner
- Simulated time steps of 10 µs (total time 6s)

#### Thanks to P. Klaus

# **COMPARISON TO SIMULATION**



Possible explanation for small mismatch:

- Worse heat conductivity
- Heat capacity is higher than assumed
- Mismatch between reference points in measurement and experiment

### SUMMARY



An experimental set up was constructed up to measure the thermal features of TPG in vacuum.

An analytic function was used to fit our measurements.

 Numerical simulation was used to model our geometry realistically and to understand the material properties by changing them.

# BROKENTPG



### THERMAL PERFORMANCE: SLOW RISE FIT



The second fit, within the time of t = 16 - 175s, characterize the saturations phase.

 $\tau_{slow,TPG \ 254um} = 31s$  $\tau_{slow,TPG \ 500um} = 48s$ 

The long relaxation times describe the heat capacity and the power of the cool sink to evacuate the heat on the carrier

### THERMAL PERFORMANCE: ROUNDUP



- Thickness of the material effects the heat distribution
- The plots show us:
- → the material properties of the TPG ( $\tau_{fast}$ )
- → power to evacuate the heat from the carrier  $(\tau_{slow})$
- $\tau_{fast}$  substantiate the excellent thermal performance of the TPG
- $\tau_{slow}$  will help us to improve the heat evacuation and cool sink

# OVERVIEW: MVD



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Micro Vertex Detector (MVD)

- I<sup>st</sup> subdetector of CBM
  - → vertexing
  - → micro-tracking
- 4 planar station, divided in quadrants
- Equipped with CMOS Sensors, which have to be cooled to ensure their efficiency
- Operates in vacuum

# HEAT CONDUCTIVITIES IN COMPARISON



thermal conductivity [W/mK]